

ER SHEET U.S. DEPARTMENT OF COMMERCE PTO-1595 Patent and Trademark Office 102040023 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. Name of conveying party(ies): 2 Name and address of receiving party(ies): Po-Tao Chu Taiwan Semiconductor Manufacturing Co. Ltd. Hsin-Yuan Chen 3-19-02 No. 121 Park Avenue 3 Chung-Jen Chen Science-Based Industrial Park Tai-Ming Yang Hsin-Chu, Taiwan, R.O.C. Cheng-Ming Wu Nature of conveyance: Additional name(s) & address(es) attached □ Yes 図 No Assignment Merger Security Agreement ☐ Change of Name Other: Execution Date:_ Jan. 29, 2002 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: __01-29-02 A. Patent Application No(s). B. Patent No(s) 10,102288 Additional numbers attached? □ Yes ☑ No Total number of applications and patents involved: Name and address of party to whom correspondence concerning document should be mailed: RANDY W. TUNG Total fee (37 CFR 3.41) \$40.00 Tung & Associates 838 W. Long Lake Road **Enclosed** Suite 120 Bloomfield Hills, Michigan 48302 Authorized to charge credit card (w/filing fee) Deposit Account Number: 08/25/2002 MGEBREM1 00000020 10102288 (Attach duplicate copy of this page if paying by deposit 02 FC 581 40.00 DP account) DO NOT USE THIS SPACE 9 Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Randy W. Tung March 19, 2002 Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

67,200-474

Registration No. 31,311

ASSIGNMENT

WHEREAS, we, <u>PAUL CHU, HSIN-YUAN CHEN, CHUNG-JEN CHEN, TAI-MING YANG and CHENG-MING WU</u> have invented certain improvements in PHOTORESIST REMOVAL FROM ALIGNMENT MARKS THROUGH WAFER EDGE EXPOSURE for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

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in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Cheng-Mong Win

CETING-IEN CHEN TALMING YANG

HSIN-YILAN CHEN

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

RECORDED: 03/19/2002

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